

PS7341-1B,PS7341L-1B

HIGH ISOLATION VOLTAGE 6-PIN DIP OCMOS FET (1-ch OCMOS FET)

DESCRIPTION

The PS7341-1B and PS7341L-1B are solid state relays containing a GaAs LED on the light emitting side (input side) and normally close (N.C.) contact MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7341L-1B has a surface mount type lead.

FEATURES

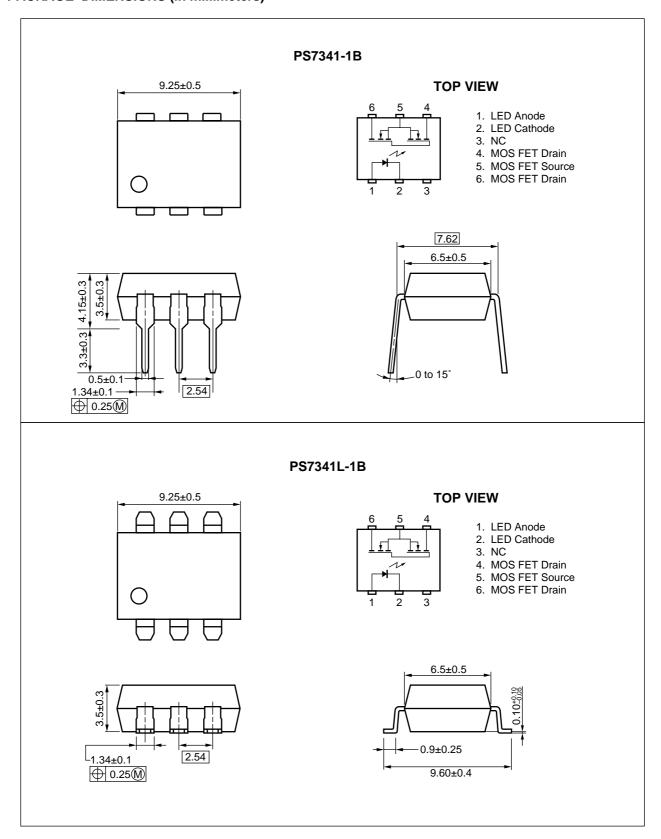
- High isolation voltage (BV = 3 750 Vr.m.s.)
- 1 channel type (1 b output)
- Low LED Operating Current (IF = 2 mA)
- · Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- Low offset voltage
- PS7341L-1B: Surface mount type
- UL approved: File No. E72422 (S)
- BSI approved: No. 8252/8253
- CSA approved: CA 101391

APPLICATIONS

- · Exchange equipment
- Measurement equipment
- FA/OA equipment

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

PACKAGE DIMENSIONS (in millimeters)



ORDERING INFORMATION (Solder Contains Lead)

Part Number	Package	Packing Style	Application Part Number*1
PS7341-1B	8-pin DIP	Magazine case 50 pcs	PS7341-1B
PS7341L-1B			PS7341L-1B
PS7341L-1B-E3		Embossed Tape 1 000 pcs/reel	
PS7341L-1B-E4			

^{*1} For the application of the Safety Standard, following part number should be used.

ORDERING INFORMATION (Pb-Free)

Part Number	Package	Packing Style	Application Part Number*1
PS7341-1B-A	8-pin DIP	Magazine case 50 pcs	PS7341-1B
PS7341L-1B-A			PS7341L-1B
PS7341L-1B-E3-A		Embossed Tape 1 000 pcs/reel	
PS7341L-1B-E4-A			

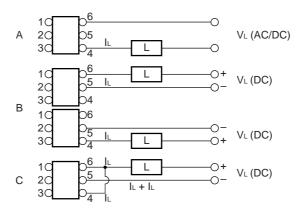
^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter			Symbol	Ratings	Unit
Diode	Forward Current (D	C)	lF	50	mA
	Reverse Voltage		VR	5.0	V
	Power Dissipation		Po	50	mW
	Peak Forward Curre	ent*1	IFP	1	Α
MOS FET	Break Down Voltage	е	VL	400	V
	Continuous Connection A		IL	150	mA
	Load Current ^{*2} Connection B Connection C			200	
				300	
	Pulse Load Current ^{*3} (AC/DC Connection)		ILP	300	mA
Power Dissipation			Po	560	mW
Isolation Voltage*4			BV	3 750	Vr.m.s.
Total Power Dissipation			PT	610	mW
Operating Ambient Temperature			TA	-40 to +85	°C
Storage Temperature			T _{stg}	-40 to +125	°C

^{*1} PW = 100 μ s, Duty Cycle = 1 %

^{*2} Conditions: IF \geq 2 mA. The following types of load connections are available.



^{*3} PW = 100 ms, 1shot

^{*4} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60 % between input and output

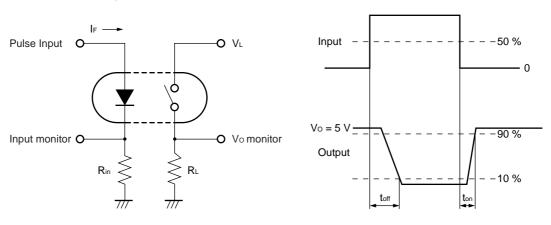
RECOMMENDED OPERATING CONDITIONS (TA = 25 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

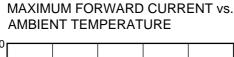
ELECTRICAL CHARACTERISTICS (TA = 25 °C)

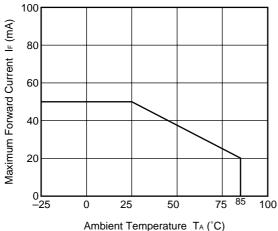
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	IR	V _R = 5 V			5.0	μА
MOS FET	Off-state Leakage Current	Loff	IF = 10 mA, VD = 400 V		0.5	10	μΑ
	Output Capacitance	Cout	IF = 10 mA, VD = 0 V, f = 1 MHz		185		pF
Coupled	LED Off-state Current	I Foff	IL = 150 mA			2.0	mA
	On-state Resistance	R _{on1}	IF = 0 mA, IL = 10 mA		20	30	Ω
		R _{on2}	IF = 0 mA, IL = 150 mA		16	25	
	Turn-on Time *1	ton	If = 10 mA, Vo = 5 V, R _L = 2 k Ω ,		0.03	0.2	ms
	Turn-off Time *1	toff	PW ≥ 10 ms		0.6	1.5	
	Isolation Resistance	Rı-o	Vi-o = 1.0 kVpc	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		1.1		pF

*1 Test Circuit for Switching Time

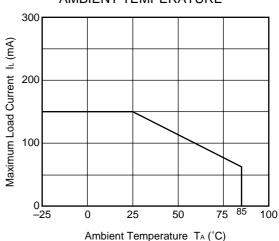


★ TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)

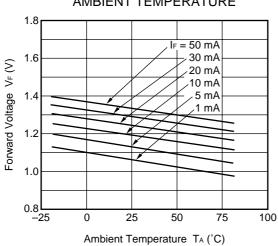




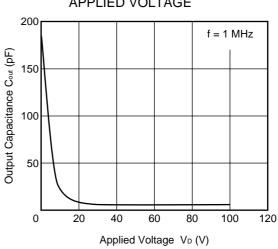
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



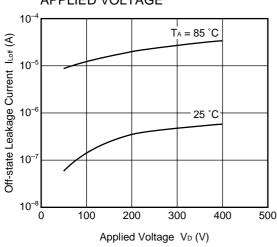
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



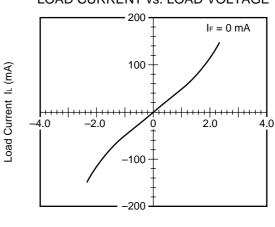
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE

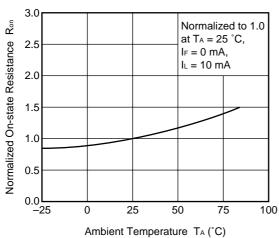


LOAD CURRENT vs. LOAD VOLTAGE

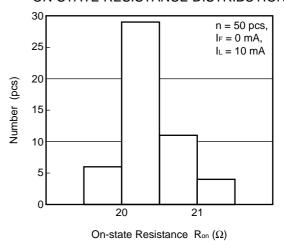


Load Voltage V_L (V)

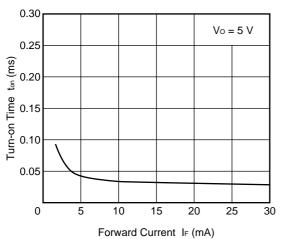
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



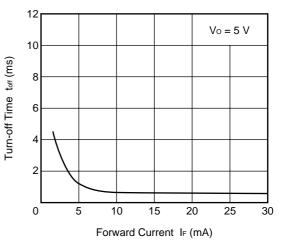
ON-STATE RESISTANCE DISTRIBUTION



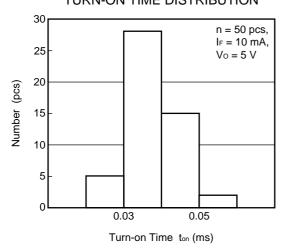
TURN-ON TIME vs. FORWARD CURRENT



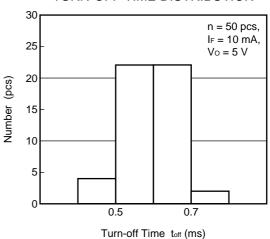
TURN-OFF TIME vs. FORWARD CURRENT



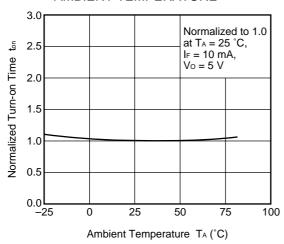
TURN-ON TIME DISTRIBUTION



TURN-OFF TIME DISTRIBUTION

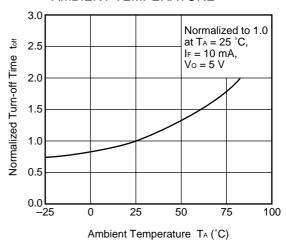


NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

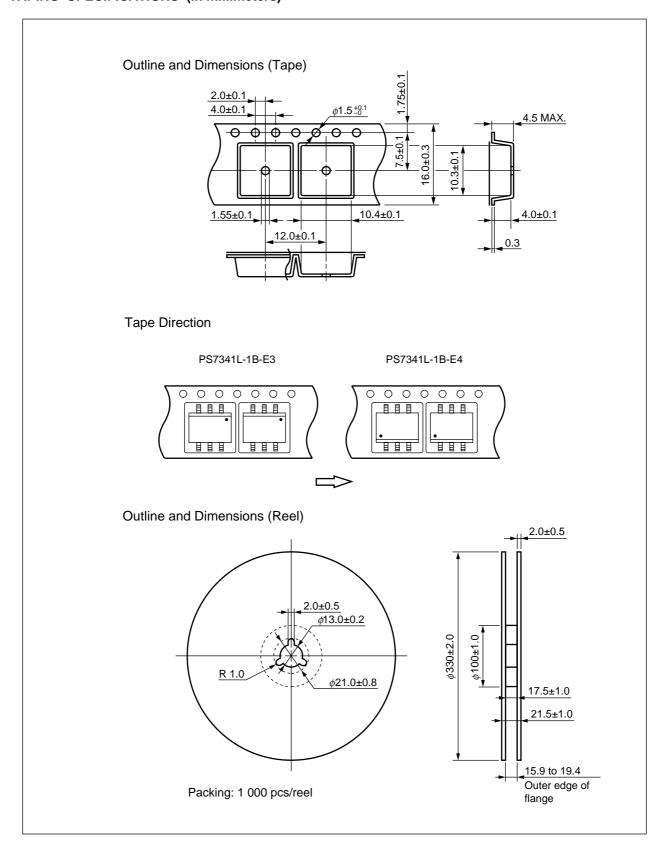


Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



★ TAPING SPECIFICATIONS (in millimeters)



* RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

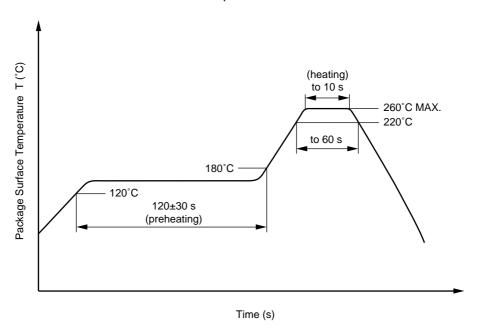
Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Two

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

• Number of times One

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.



4590 Patrick Henry Drive Santa Clara, CA 95054-1817 Telephone: (408) 919-2500

Facsimile: (408) 988-0279

Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The -AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)		on contained devices	
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

Important Information and Disclaimer: Information provided by CEL on its website or in other communications concerting the substance content of its products represents knowledge and belief as of the date that it is provided. CEL bases its knowledge and belief on information provided by third parties and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. CEL has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. CEL and CEL suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall CEL's liability arising out of such information exceed the total purchase price of the CEL part(s) at issue sold by CEL to customer on an annual basis.

See CEL Terms and Conditions for additional clarification of warranties and liability.